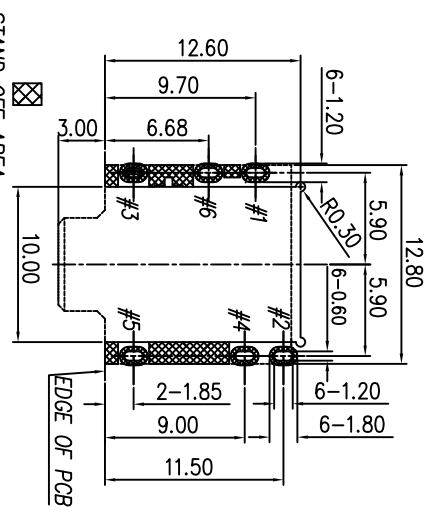
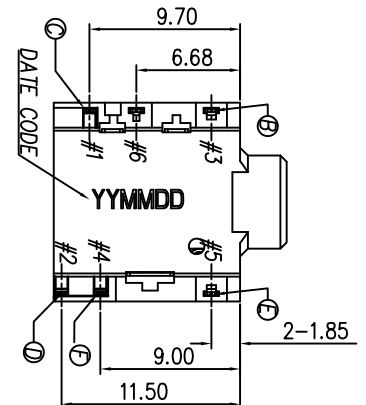
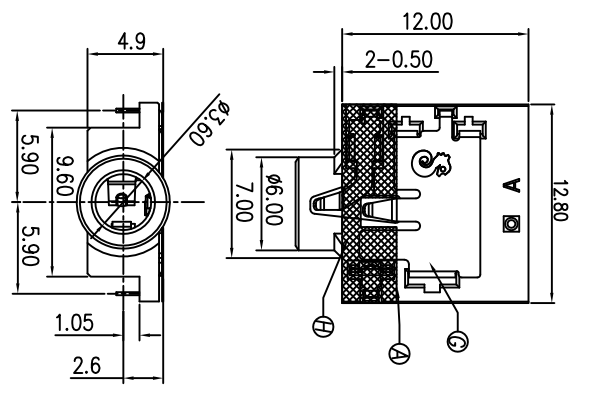
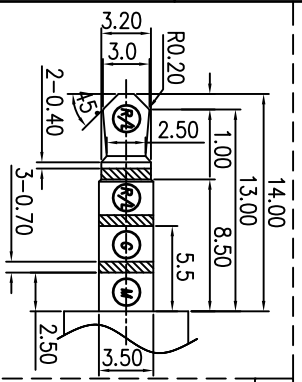
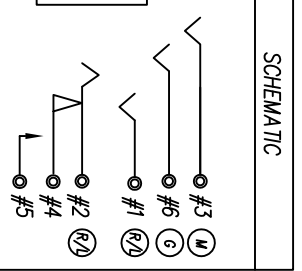


| REV/ECHN NO OR DESCRIPTION | REVISED | DATE |
|-----------------------------|---------|------------|
| A PRODUCT RELEASE | ZLS | 2012.8.3 |
| B ECE NO.: C130013 以實物修正在圖面 | ZLS | 2013.01.25 |

- SPECIFICATIONS:**
- ELECTRICAL CHARACTERISTICS:
 - RATING: 12V AC, 1A DC.
 - CONTACT RESISTANCE: 50mΩ MAX.
 - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR ONE MINUTE.
 - INSULATION RESISTANCE: 100MΩ MIN. MEASURED BY 500 VDC.
 - MECHANICAL CHARACTERISTICS:
 - INSERTION FORCE: 0.4~3.0 KGf
 - WITHDRAWAL FORCE: 0.3~2.0 KGf
 - LIFE TEST: 5,000 CYCLES MIN.
 - OTHER GENERAL SPEC. TO REFER "2SJ2285 SERIES SPEC".
 - TO CONFORM TO THE SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK: ○
 - HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING: ○
 - FOR REFLOW SOLDERING LEAD-FREE PROCESS.
 - PACKAGING: TAPE&REEL.



RECOMMENDED P.C.B. LAYOUT T=1.00
TOP VIEW (TOLERANCE: ±0.05)



| NO | DESCRIPTION | QTY | MATERIAL | PLATING & COLOR |
|----|-------------------|-----|-------------------------------------|---|
| H | MYLAR | 1 | MYLAR 0.075T | |
| G | SHIELD | 1 | COPPER ALLOY 0.20T | Gold flash on contact area all over Nickel Plated |
| F | TRANSFER TERMINAL | 1 | COPPER ALLOY 0.20T | Gold flash on contact area and Solder tab all over Nickel Plated |
| E | MAKE TERMINAL | 1 | COPPER ALLOY 0.20T | GOLD FLASH |
| D | RING | 1 | COPPER ALLOY 0.20T | Gold flash on contact area and Solder tab all over Nickel Plated |
| C | TIP | 1 | COPPER ALLOY 0.25T | GOLD FLASH |
| B | EARTH | 1 | COPPER ALLOY 0.20T | GOLD FLASH |
| A | BODY | 1 | HIGH TEMP THERMOPLASTIC UL 94V-0 | BLACK |

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: ANGLES:
X : ±0.5 X : ±2°
X.X : ±0.3 X.X : ±1°
X.XX : ±0.2

Singatron Enterprise Co., Ltd.
信晉企業股份有限公司

TITLE: 3.5mm PHONE JACK
DWN: 2012/2/17 PART NO. 2SJ2326-020111F
CHKD: 2012/2/17 SCALE 3:1 UNIT: mm
APVD: 2012/2/17 SIZE: A3 SHEET: 10F1 REV: B

CUSTOMER COPY